

APPLICATION NO. 10/026511

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CLMPTO

1. A method for manufacturing a nonreciprocal circuit device including a metal case containing central conductors, a ferrite core near the central conductors, and a permanent magnet for applying a static magnetic field to the ferrite core, the method comprising the steps of:  
forming a thermosetting resin layer on an outer surface of the metal case; and  
heating the entire nonreciprocal circuit device after adjusting the magnetic force of the permanent magnet to simultaneously thermally demagnetize the permanent magnet and harden the thermosetting resin layer.
2. The method for manufacturing a nonreciprocal circuit device according to Claim 1, wherein the heating temperature is set between 85 and 230°C.
3. The method for manufacturing a nonreciprocal circuit device according to claim 2, wherein said device comprises a high-temperature solder which melts at 230°C or higher.

CLAIMS 4-14 (CANCELLED)